505765202 11/08/2019

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5812018

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SU-IL CHO	05/28/2019
SUNG-YOON RYU	05/28/2019
YU-SIN YANG	05/28/2019
CHI-HOON LEE	05/28/2019
HYUN-SU KWAK	08/05/2019
JUNG-WON KIM	08/05/2019

RECEIVING PARTY DATA

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City:	SUWON-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
Postal Code:	16677
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Name: Street Address:	KOREA ADVANCED INSTITUTE OF SCIENCE AND TECHNOLOGY 291, DAEHAK-RO, YUSEONG-GU
Street Address:	291, DAEHAK-RO, YUSEONG-GU

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16678755

CORRESPONDENCE DATA

Fax Number: (703)207-0003

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using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Correspondent Name: LEE & MORSE, P.C.

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Address Line 2: SUITE 500

Address Line 4: FALLS CHURCH, VIRGINIA 22042

ATTORNEY DOCKET NUMBER:	249/1224_00
NAME OF SUBMITTER:	EUGENE M. LEE
SIGNATURE:	/Eugene M. Lee/
DATE SIGNED:	11/08/2019
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 5

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COMBINED DECLARATION (37 CFR §1.63) FOR UTILITY PATENT APPLICATION AND ASSIGNMENT FORM

The undersigned acknowledges that this document is being used both as an assignment of the invention and as the declaration (37 CFR 1.63) for a Utility or Design Application.

WHER	EAS, the undersigned, hereinafter referred to collectively as Assignor	has invented:
Title:	THICKNESS PREDICTION NETWORK LEARNING METHO SEMICONDUCTOR DEVICE MANUFACTURING METHOD SEMICONDUCTOR MATERIAL DEPOSITION EQUIPMENT	DD, AND
for whice patent.	ch Assignor is about to make or has made United States or Internation	al application for
WHER.	EAS, as a below named inventor(s), I/(we) hereby declare that:	
Section	I. Declaration	
	claration is directed to the attached U.S. non-provisional patent applicage is marked:	ation, unless the
	U.S. non-provisional patent application number, or	, filed on
	PCT international patent application number	, filed on
	as amended by the Preliminary Amendment attached hereto	
The abo	ve-identified application was made or authorized to be made by me (c	s).
	elieve that I am (we are) the original inventor (original joint inventors n in the above-identified application.	of a claimed
	ereby acknowledge that any willful false statement made in this declar B U.S.C. 1001 by fine or imprisonment of not more than five (5) years	
	state that I have reviewed and understand the contents of the above ic on, including the claims (as amended by any amendment referred to a	
This fo	rm requires the use of an Application Data Sheet.	
SEC Ref	No. <u>IH-201806-005-1-US0</u> Attorney Ref No. <u>248</u>	/1224_00
CO:	MBINED DECLARATION (37 CFR 1.63) FOR UTILITY PATENT APPL	CATION AND

COMBINED DECLARATION (37 CFR 1.63) FOR UTILITY PATENT APPLICATION AND ASSIGNMENT FORM
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I acknowledge that I am aware of the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56.

Section II. Assignment

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned, the undersigned hereby sell(s) and assign(s) to

Samsung Electronics Co., Ltd.

having an address at 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do 16677, Republic of Korea; and

Korea Advanced Institute of Science and Technology

having an address at 291, Daehak-ro, Yuseong-gu, Daejcon-si, 34141, Republic of Korea;

(collectively "Assignees"), the entire (100%) right, title and interest for the United States as defined in 35 USC §100, in the invention described in the application identified in Section I of this document.

Assignor hereby confirms any prior assignment to Assignee, and to the extent that Assignor has not already done so, agrees to assign, and hereby does, sell, assign and transfer unto Assignee and its successors in interest, the full and exclusive right, title and interest in the United States of America and throughout the world, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, to the inventions as described in the aforesaid ap

continuations-in-part, or other applications claiming priority directly or indirectly from the aforesaid application, and any United States or foreign Letters Patent, utility model, or other similar rights which may be granted thereon, including reissues, reexaminations and extensions thereof, and all copyright rights throughout the world in the aforesaid application and the subject matter disclosed therein, these rights, title and interest to be held and enjoyed by Assignee to the full end of the term for which the Letters Patent, utility model, or other similar rights, are granted and any extensions thereof as fully and entirely as the same would have been held by Assignor had this assignment and sale not been made, and the right to sue for, and recover for past infringements of, or liabilities for, any of the rights relating to any of the applications, patents, utility models, or other similar rights, resulting therefrom, and the copyright rights;

Assignor hereby covenants and agrees to execute all instruments or documents required or requested for the making and prosecution of any applications of any type for patent, utility model, or other similar rights, and for copyright, in the United States and in all foreign countries including, but not limited to, any provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, and as to letters patent any reissue, re-examination, or extension thereof, and for litigation regarding, or for the purpose of protecting title and to the said

SEC Ref No.	<u>IH-201806-005-1-US0</u>	Attorney Ref No.	249/1224_00

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invention, the United States application for patent, or Letters Patent therefor, and to testify in support thereof, for the benefit of Assignee without further or other compensation than that above set forth;

Assignor hereby covenants that no assignment, sale, license, agreement or encumbrance has been or will be entered into which would conflict with this Assignment; and

Assignor hereby requests the United States Patent and Trademark Office to issue the Letters Patent of the United States of America to Assignee, and requests that any official of any country or countries foreign to the United States, whose duty it is to issue or grant patents and applications as aforesaid, to issue the Letters Patent, Utility Model Registration or other similar right to Assignee.

The undersigned hereby grant(s) the law firm of LEE & MORSE, P.C. the power to insert on this Declaration and Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

Section III. Inventor(s)/Assignor(s) Signature(s)

LEGAL NAME OF	Family Name	First Given Name	Second Given Name
FIRST INVENTOR/ASSIGNOR	СНО	Su-il	
	3		· ·
SIGNATURE	and the second	DATE	2019, 5,28

SEC Ref No.	TH-201806-005-1-US0	Attorney Ref No.	249/1224_00
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LEGAL NAME OF	Family Marac	First Given Name	C
SECOND	Family Name	ritse Given Name	Second Given Name
INVENTOR/ASSIGNOR	RYU	Sung-yoon	
	of of materials		
Oron Loron P	J440_		2000 000
SIGNATURE		DATE	2019.5.28
LEGAL NAME OF	Family Name	First Given Name	Second Given Name
THIRD INVENTOR/ASSIGNOR	YANG	Yu-sin	
INVENTOR/ASSIGNOR			
	System Spark		1.1
SIGNATURE _	Yma, Yusin	DATE	2019/5/28
			,
LEGAL NAME OF	Family Name	First Given Name	Second Given Name
FOURTH	LEE	Chi-hoon	
INVENTOR/ASSIGNOR	LDE	Carnoon	
i		<u></u>	
SIGNATURE	244	DATE	2019, 4. 28
al the second	<i></i>		
and have	e was a rice	and Backla	248/2224 50
SEC Ref No. IH-201800	5-005-1-US0 Attor	ney Ket INO,	249/1224_00
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COMBINED DECLARATION (37 CFR 1.63) FOR UTILITY PATENT APPLICATION AND ASSIGNMENT FORM

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LEGAL NAME OF FIFTH	Family Name	First Given Name	Second Given Name
INVENTOR/ASSIGNOR	KWAK	Hyun-su	
SIGNATURE	an_	DATE	2019.08.05

Family Name	First Given Name	Second Given Name
KIM	Jung-won	

7/2	DATE	DD19.08.05
	*	KIM Jung-won

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